

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)
2. (Currently Amended) A conductive bump for a semiconductor chip that has a pad-mounting surface which is provided with at least a bonding pad thereon, said conductive bump comprising:
 - a first metal layer adapted to be bonded to the bonding pad;
 - a conductive paste body formed on said first metal layer; and
 - a second metal layer formed on said paste body such that said paste body is sandwiched between said first and second metal layers;said first metal layer also has a base portion bonded to said bonding pad, and being in contact with said second metal layer through a peripheral portion extending from said base portion in a transverse direction relative to said base portion and cooperating with said base portion to confine a recess therebetween, said conductive paste body filling said recess, said recess being closed by said second metal layer.
- 3.-4. (Canceled).
5. (Previously Presented) The conductive bump of claim 2, wherein said conductive paste comprises a thermosetting resin and a conductive filler.
6. (Canceled)